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(57) **ABSTRACT**

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(63) Continuation of application No. 17/956,773, filed on Sep. 29, 2022, now Pat. No. 11,967,580, which is a continuation of application No. 17/706,156, filed on Mar. 28, 2022, now Pat. No. 11,749,642, which is a continuation of application No. 17/128,558, filed on Dec. 21, 2020, now Pat. No. 11,437,348, which is a continuation of application No. 16/648,464, filed on

Microelectronic assemblies, and related devices and methods, are disclosed herein. For example, in some embodiments, a microelectronic assembly may include a package substrate, a first die coupled to the package substrate with first interconnects, and a second die coupled to the first die with second interconnects, wherein the second die is coupled to the package substrate with third interconnects, a communication network is at least partially included in the first die and at least partially included in the second die, and the communication network includes a communication pathway between the first die and the second die.

